Schottky Barrier Diode

DB2441700L

# **Panasonic**

## DB2441700L

## Silicon epitaxial planar type

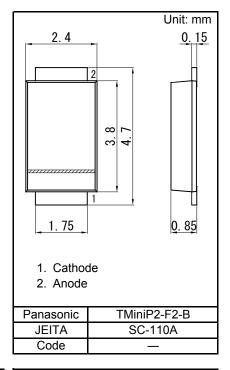
#### For rectification

#### ■ Features

- · Low forward voltage VF
- Forward current (Average) IF(AV) = 5 A rectification is possible
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: 4W

#### ■ Packaging

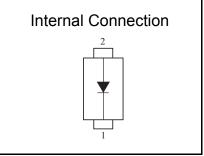
Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)



#### ■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Reverse voltage	VR	40	V
Repetitive peak reverse voltage	VRRM	40	V
Forward current (Average)*1	IF(AV)	5.0	Α
Non-repetitive peak forward surge current *2	IFSM	50	Α
Junction temperature	Tj	125	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-40 to +125	°C

Note: \*1 For embedded alumina substrate (substrate size: 5 cm× 5 cm)



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<sup>\*2 50</sup> Hz sine wave 1 cycle (Non-repetitive peak current)

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■ Electrical Characteristics Ta = 25 °C ± 3 °C

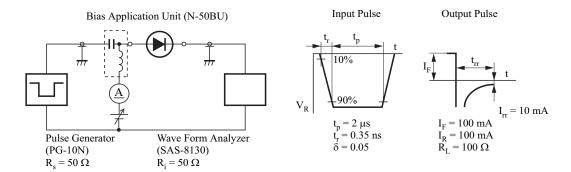
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	IF = 5.0 A		0.47	0.54	V
Reverse current	IR	VR = 40 V		60	300	μA
Terminal capacitance	Ct	VR = 10 V, f = 1 MHz		95		pF
Reverse recovery time *1	trr	IF = IR = 100 mA		30		ns
		Irr = 10 mA, RL = 100 $\Omega$				

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.
  - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
  - 3. \*1 trr test circuit

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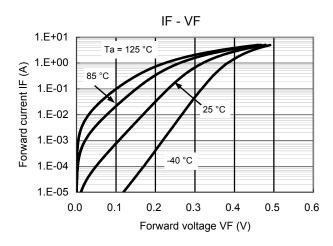
Revised

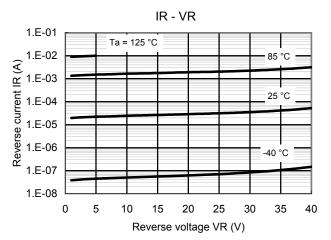


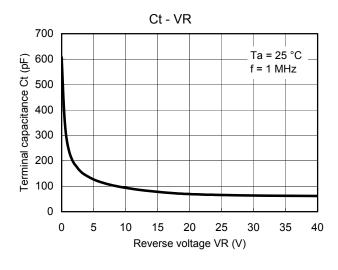
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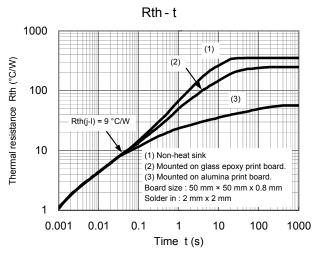
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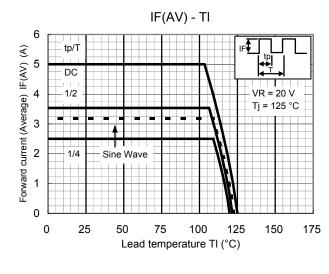
## Technical Data (reference)

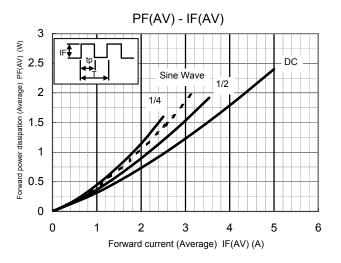












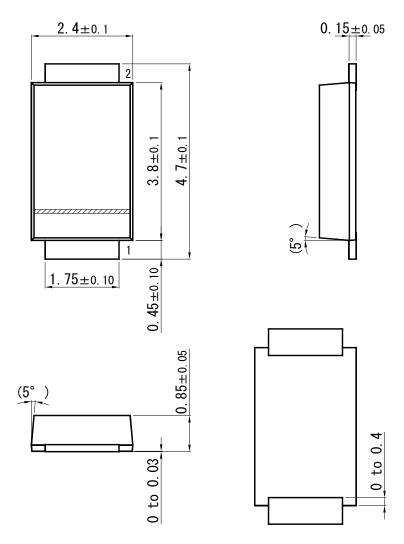
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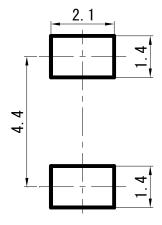
## TMiniP2-F2-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)

Established: 2010-03-01 Revised: 2013-04-19



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